

2822

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PATENT APPLICATION

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

6/A Amold  
11-20-02  
A. Wade

In re Patent Application of

Lloyd G. Burrell et al.

Serial No.: 09/805,027

Group Art Unit: 2822

Filed: March 12, 2001

Examiner: M. Lewis

For: COPPER TO ALUMINUM INTERLAYER INTERCONNECT USING  
STUD AND VIA LINER

Commissioner of Patents and Trademarks  
Washington, D.C. 20231

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AMENDMENT UNDER 37 C. F. R. §1.111

Sir:

In response to the Office Action mailed August 14, 2002, please amend the above-identified application as follows:

In the claims:

Please substitute the following claim 1 for the like-numbered claim as originally filed. A marked up copy of this claim showing the current changes is attached as an appendix to this amendment.

- sub 2
1. (Amended) An integrated circuit including
- a patterned copper layer,
  - a patterned aluminum layer,
  - a stud connection in an opening in a layer of material between a location on said patterned copper layer and a location on said patterned aluminum layer, and
  - a liner in said opening and extending between said stud connection and said location on said patterned copper layer.